

Appl. No. 10/707,824
Amdt. dated January 23, 2006
Reply to Office action of October 24, 2005

No amendments have been made to the claims, and the claims are listed merely for reference:

Listing of Claims:

1. (original) A method of defect review comprising following steps:
5 providing a wafer with a plurality of defects;
performing a defect inspection to detect the defects;
performing an automatic defect classification according to a database to separate the defects into a plurality of defect types; and
performing a defect review;
10 wherein each defect type has different sampling ratios in the defect review according to its influence degree of process yield.
2. (original) The method of claim 1 wherein the database comprises information about the plurality of defect types and defect information corresponding to each defect type.
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3. (original) The method of claim 2 wherein the defect information comprises the influence-degree of the process yield of each defect type.
4. (original) The method of claim 3 wherein the database separates the defect types
20 into killer defects and non-killer defects according to the influence degree of the process yield.
5. (original) The method of claim 4 wherein the sampling ratio of the killer defects in the defect review is larger than that of the non-killer defects.
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6. (original) The method of claim 3 wherein the database separates the defects into pre-layer defects and adding defects, and further separates the adding defects into killer defects and non-killer defects.

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7. (original) The method of claim 6 wherein the defect review focuses on the adding defects.
- 5 8. (original) The method of claim 1 wherein after finishing the defect inspection, a judgment of cluster defects is performed and a defect review with a high sampling ratio is performed on the cluster defects if the cluster defects exist.
9. (original) The method of claim 1 wherein the database is updated according to the
- 10 result of the defect review after finishing the defect review.